

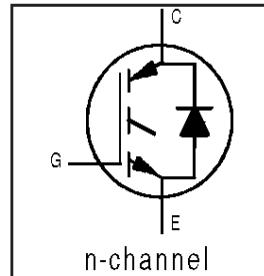
IRG4PH40KDPbF

INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

Short Circuit Rated
UltraFast IGBT

Features

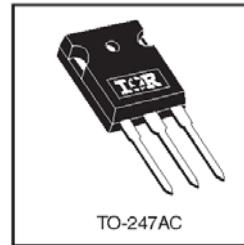
- High short circuit rating optimized for motor control, $t_{sc} = 10\mu s$, $V_{CC} = 720V$, $T_J = 125^{\circ}C$, $V_{GE} = 15V$
- Combines low conduction losses with high switching speed
- Tighter parameter distribution and higher efficiency than previous generations
- IGBT co-packaged with HEXFRED™ ultrafast, ultrasoft recovery antiparallel diodes
- Lead-Free



$V_{CES} = 1200V$
 $V_{CE(on)} \text{ typ.} = 2.74V$
 $@ V_{GE} = 15V, I_C = 15A$

Benefits

- Latest generation 4 IGBT's offer highest power density motor controls possible
- HEXFRED™ diodes optimized for performance with IGBTs. Minimized recovery characteristics reduce noise, EMI and switching losses
- This part replaces the IRGPH40KD2 and IRGPH40MD2 products
- For hints see design tip 97003



Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	1200	V
$I_C @ T_C = 25^{\circ}C$	Continuous Collector Current	30	A
$I_C @ T_C = 100^{\circ}C$	Continuous Collector Current	15	
I_{CM}	Pulsed Collector Current ①	60	
I_{LM}	Clamped Inductive Load Current ②	60	
$I_F @ T_C = 100^{\circ}C$	Diode Continuous Forward Current	8.0	W
I_{FM}	Diode Maximum Forward Current	130	
t_{sc}	Short Circuit Withstand Time	10	
V_{GE}	Gate-to-Emitter Voltage	± 20	
$P_D @ T_C = 25^{\circ}C$	Maximum Power Dissipation	160	°C
$P_D @ T_C = 100^{\circ}C$	Maximum Power Dissipation	65	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw	10 lbf·in (1.1 N·m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
R_{eJC}	Junction-to-Case - IGBT	—	—	0.77	°C/W
R_{eJC}	Junction-to-Case - Diode	—	—	1.7	
R_{eCS}	Case-to-Sink, flat, greased surface	—	0.24	—	
R_{eJA}	Junction-to-Ambient, typical socket mount	—	—	40	
Wt	Weight	—	6 (0.21)	—	g (oz)

Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(\text{BR})\text{CES}}$	Collector-to-Emitter Breakdown Voltage③	1200	—	—	V	$V_{GE} = 0\text{V}$, $I_C = 250\mu\text{A}$
$\Delta V_{(\text{BR})\text{CES}/\Delta T_J}$	Temperature Coeff. of Breakdown Voltage	—	0.37	—	V/ $^\circ\text{C}$	$V_{GE} = 0\text{V}$, $I_C = 1.0\text{mA}$
$V_{CE(\text{on})}$	Collector-to-Emitter Saturation Voltage	—	2.74	3.4	V	$I_C = 15\text{A}$ $V_{GE} = 15\text{V}$
		—	3.29	—		$I_C = 30\text{A}$ See Fig. 2, 5
		—	2.53	—		$I_C = 15\text{A}$, $T_J = 150^\circ\text{C}$
$V_{GE(\text{th})}$	Gate Threshold Voltage	3.0	—	6.0		$V_{CE} = V_{GE}$, $I_C = 250\mu\text{A}$
$\Delta V_{GE(\text{th})/\Delta T_J}$	Temperature Coeff. of Threshold Voltage	—	-3.3	—	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}$, $I_C = 250\mu\text{A}$
g_{le}	Forward Transconductance ④	8.0	12	—	S	$V_{CE} = 100\text{V}$, $I_C = 15\text{A}$
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	μA	$V_{GE} = 0\text{V}$, $V_{CE} = 1200\text{V}$
		—	—	3000		$V_{GE} = 0\text{V}$, $V_{CE} = 1200\text{V}$, $T_J = 150^\circ\text{C}$
V_{FM}	Diode Forward Voltage Drop	—	2.6	3.3	V	$I_C = 8.0\text{A}$ See Fig. 13
		—	2.4	3.1		$I_C = 8.0\text{A}$, $T_J = 125^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 100	nA	$V_{GE} = \pm 20\text{V}$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	94	140	nC	$I_C = 15\text{A}$
Q_{ge}	Gate - Emitter Charge (turn-on)	—	14	22		$V_{CC} = 400\text{V}$ See Fig. 8
Q_{gc}	Gate - Collector Charge (turn-on)	—	37	55		$V_{GE} = 15\text{V}$
$t_{d(on)}$	Turn-On Delay Time	—	50	—	ns	
t_r	Rise Time	—	31	—		$T_J = 25^\circ\text{C}$
$t_{d(off)}$	Turn-Off Delay Time	—	96	140		$I_C = 15\text{A}$, $V_{CC} = 800\text{V}$
t_f	Fall Time	—	220	330		$V_{GE} = 15\text{V}$, $R_G = 10\Omega$
E_{on}	Turn-On Switching Loss	—	1.31	—	mJ	Energy losses include "tail" and diode reverse recovery
E_{off}	Turn-Off Switching Loss	—	1.12	—		See Fig. 9, 10, 18
E_{ts}	Total Switching Loss	—	2.43	2.8		
t_{sc}	Short Circuit Withstand Time	10	—	—	μs	$V_{CC} = 720\text{V}$, $T_J = 125^\circ\text{C}$ $V_{GE} = 15\text{V}$, $R_G = 10\Omega$, $V_{CPK} < 500\text{V}$
$t_{d(on)}$	Turn-On Delay Time	—	49	—	ns	$T_J = 150^\circ\text{C}$, See Fig. 10, 11, 18
t_r	Rise Time	—	33	—		$I_C = 15\text{A}$, $V_{CC} = 800\text{V}$
$t_{d(off)}$	Turn-Off Delay Time	—	290	—		$V_{GE} = 15\text{V}$, $R_G = 10\Omega$,
t_f	Fall Time	—	440	—		Energy losses include "tail" and diode reverse recovery
E_{ts}	Total Switching Loss	—	5.1	—	mJ	Measured 5mm from package
L_E	Internal Emitter Inductance	—	13	—	nH	
C_{ies}	Input Capacitance	—	1600	—	pF	$V_{GE} = 0\text{V}$
C_{oes}	Output Capacitance	—	77	—		$V_{CC} = 30\text{V}$ See Fig. 7
C_{res}	Reverse Transfer Capacitance	—	26	—		$f = 1.0\text{MHz}$
t_{rr}	Diode Reverse Recovery Time	—	63	95	ns	$T_J = 25^\circ\text{C}$ See Fig.
		—	106	160		$T_J = 125^\circ\text{C}$ 14
I_{rr}	Diode Peak Reverse Recovery Current	—	4.5	8.0	A	$T_J = 25^\circ\text{C}$ See Fig.
		—	6.2	11		$T_J = 125^\circ\text{C}$ 15
Q_{rr}	Diode Reverse Recovery Charge	—	140	380	nC	$T_J = 25^\circ\text{C}$ See Fig.
		—	335	880		$T_J = 125^\circ\text{C}$ 16
$di_{(rec)M}/dt$	Diode Peak Rate of Fall of Recovery During t_b	—	133	—	A/μs	$T_J = 25^\circ\text{C}$ See Fig.
		—	85	—		$T_J = 125^\circ\text{C}$ 17

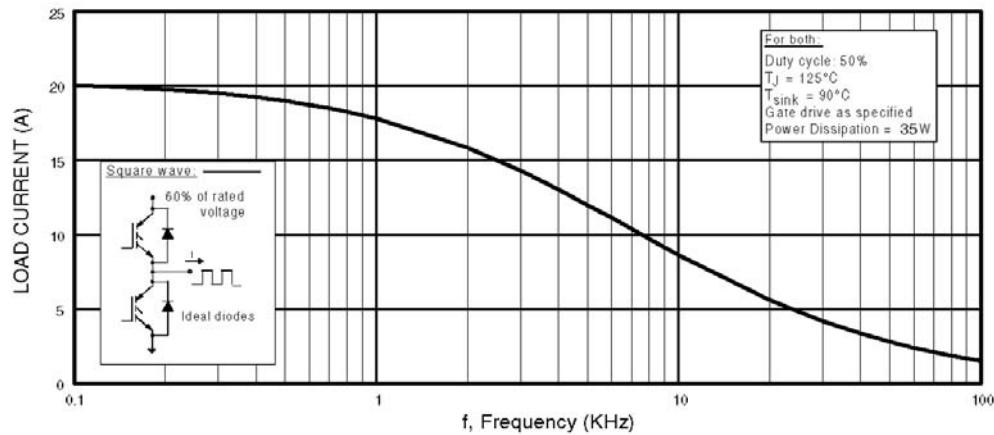


Fig. 1 - Typical Load Current vs. Frequency
 (Load Current = I_{RMS} of fundamental)

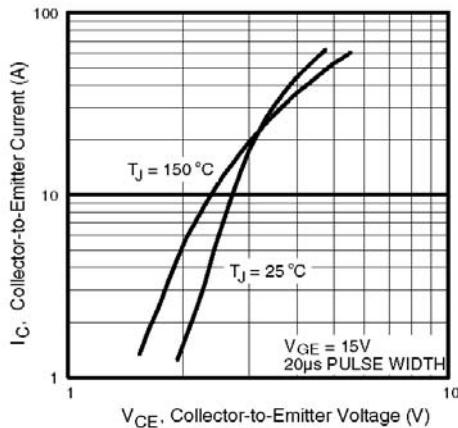


Fig. 2 - Typical Output Characteristics

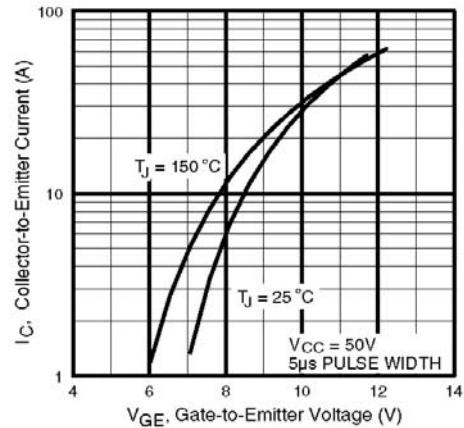


Fig. 3 - Typical Transfer Characteristics

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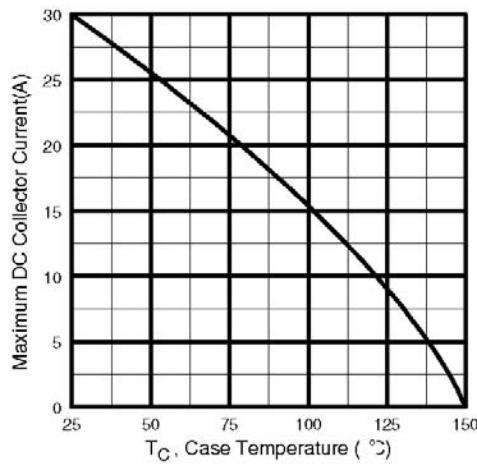


Fig. 4 - Maximum Collector Current vs. Case Temperature

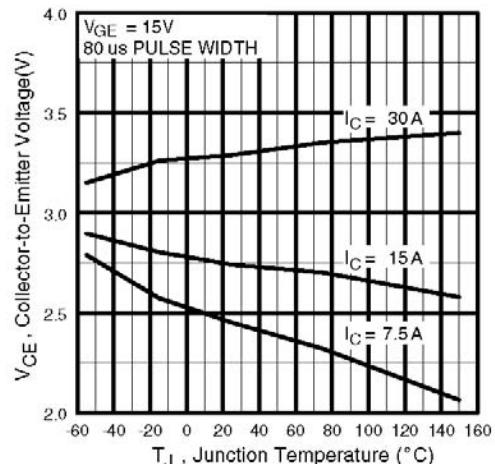


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

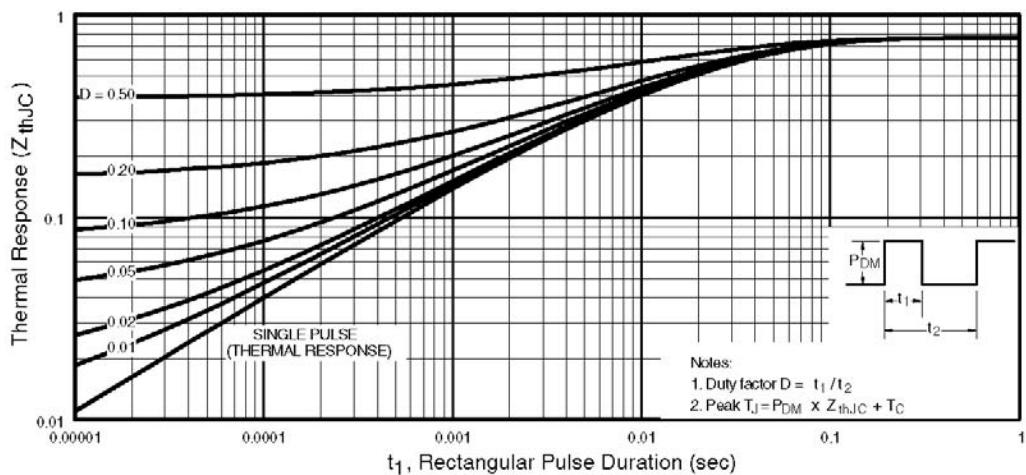
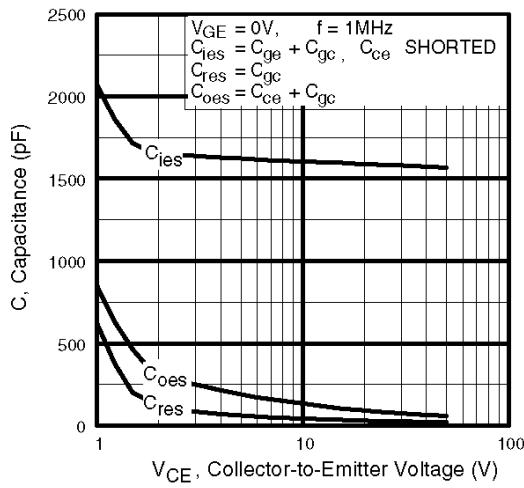
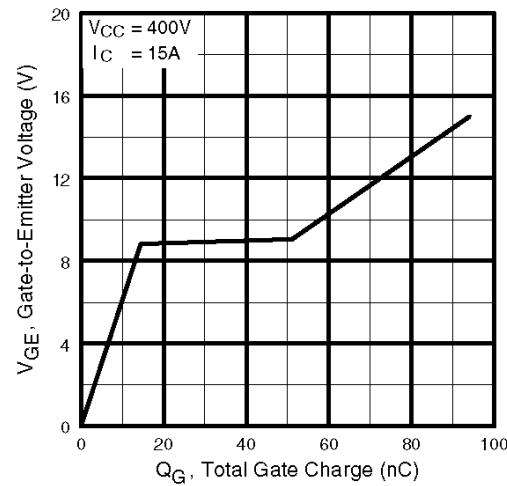


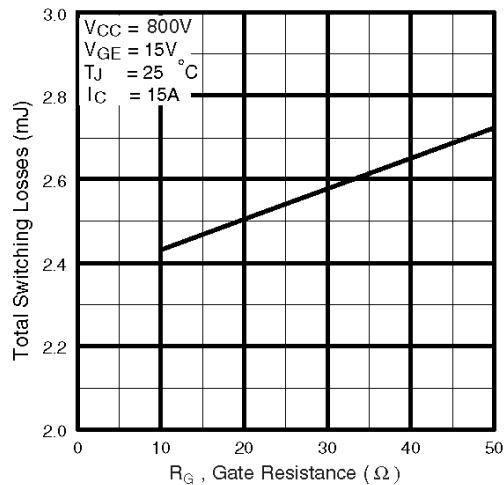
Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



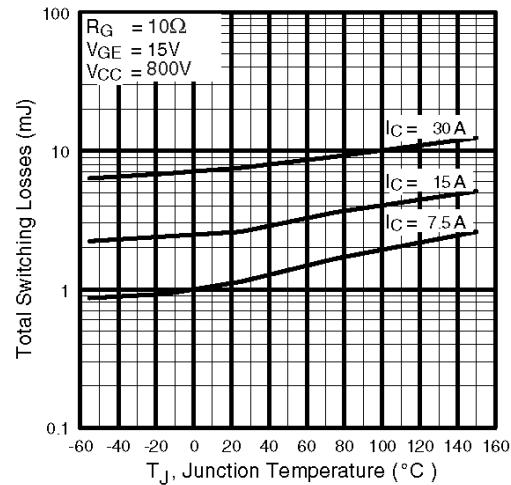
**Fig. 7 - Typical Capacitance vs.
Collector-to-Emitter Voltage**



**Fig. 8 - Typical Gate Charge vs.
Gate-to-Emitter Voltage**



**Fig. 9 - Typical Switching Losses vs. Gate
Resistance**



**Fig. 10 - Typical Switching Losses vs.
Junction Temperature**

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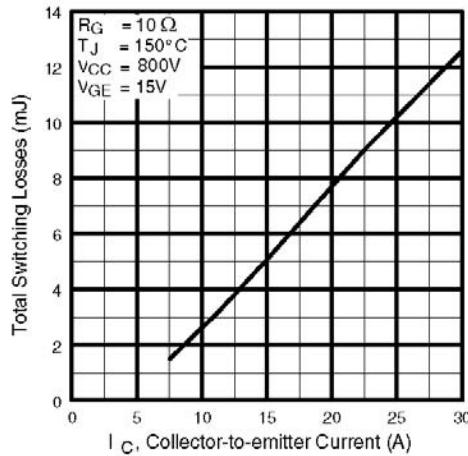


Fig. 11 - Typical Switching Losses vs.
Collector-to-Emitter Current

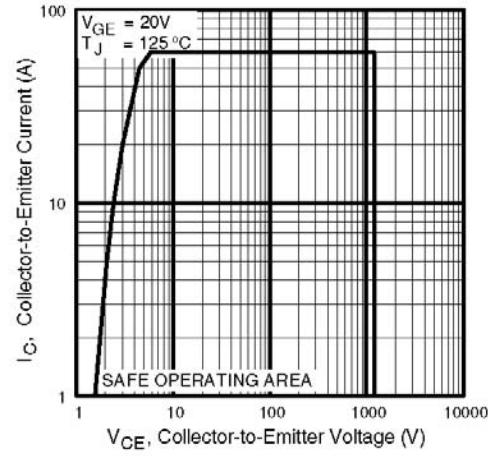


Fig. 12 - Turn-Off SOA

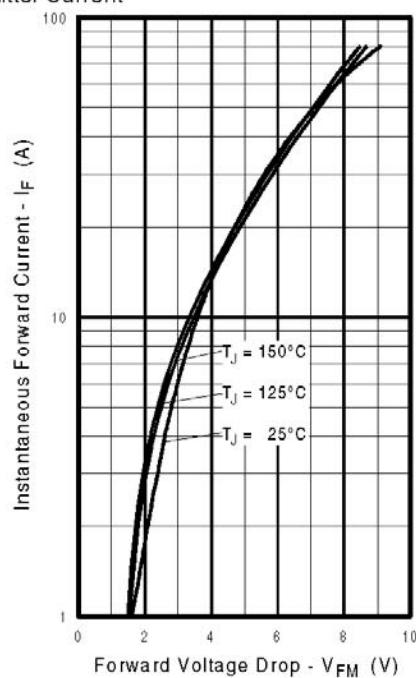


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

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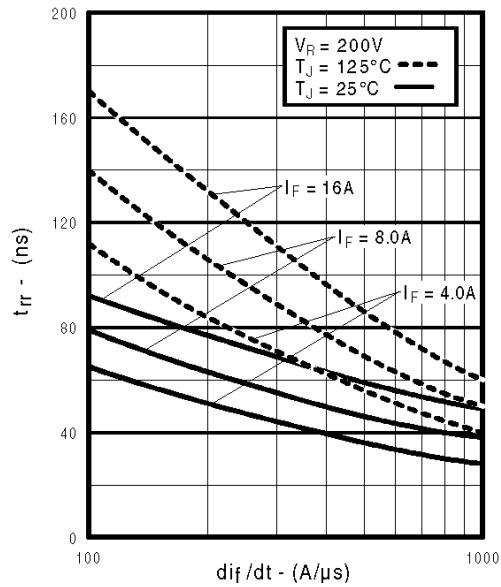


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

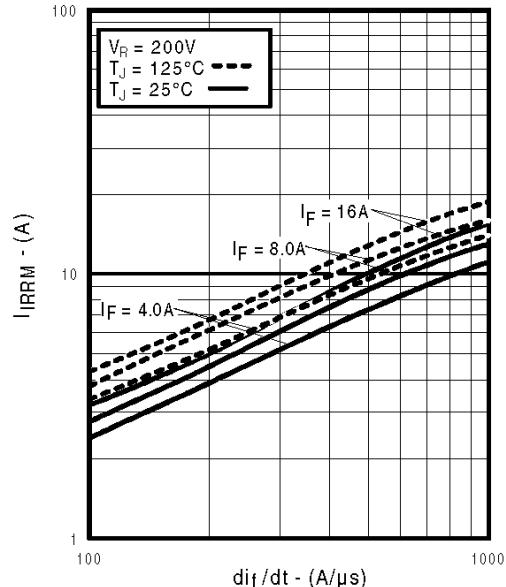


Fig. 15 - Typical Recovery Current vs. di_f/dt

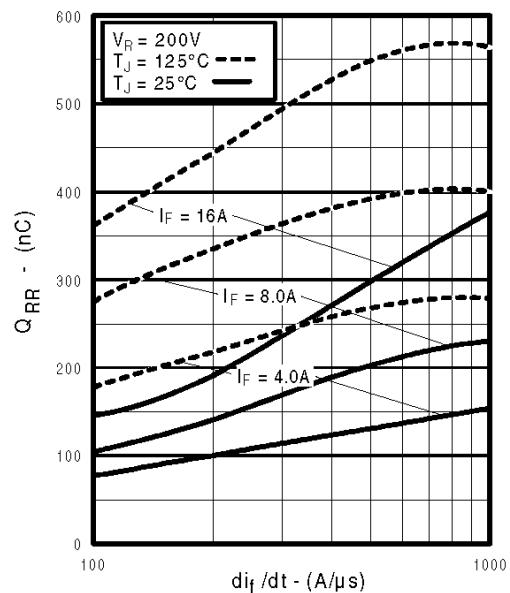


Fig. 16 - Typical Stored Charge vs. di_f/dt

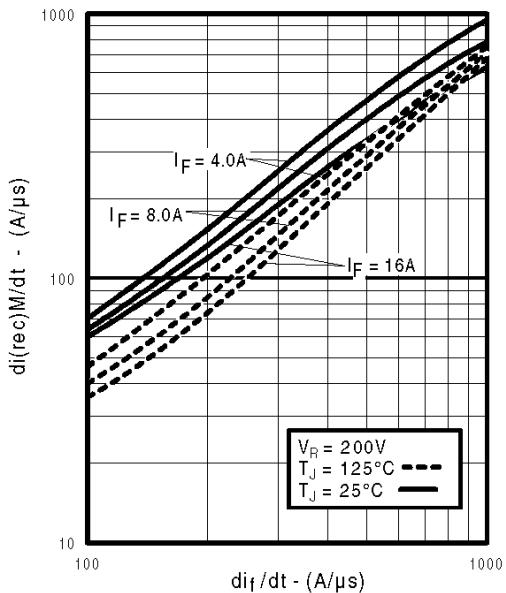


Fig. 17 - Typical $d_{(rec)}M/dt$ vs. di_f/dt

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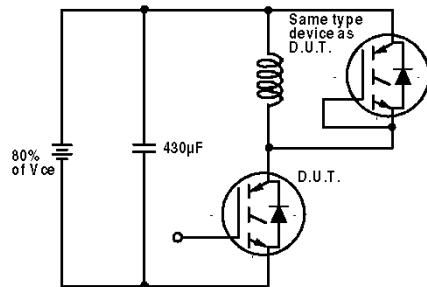


Fig. 18a - Test Circuit for Measurement of I_{LM} , E_{on} , $E_{off(diode)}$, t_{rr} , Q_m , I_{rr} , $t_d(on)$, t_r , $t_d(off)$, t_f

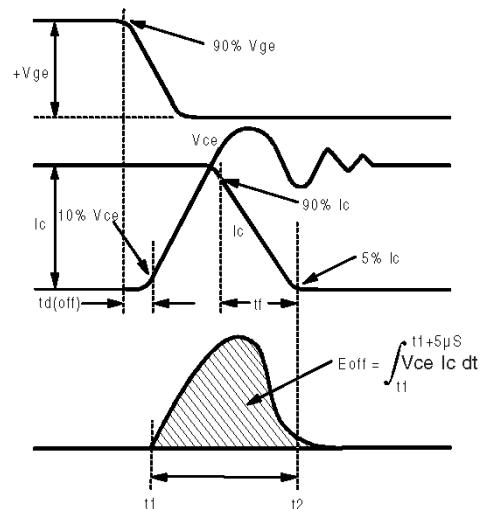


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining E_{off} , $t_{d(off)}$, t_f

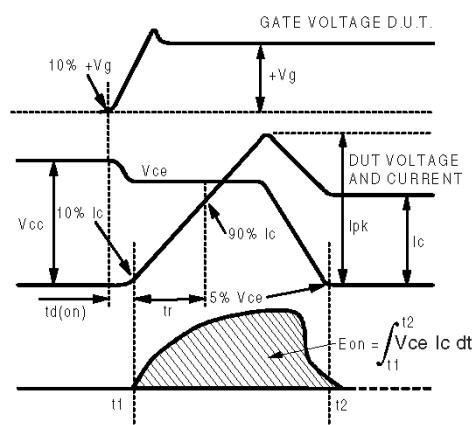


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining E_{on} , $t_{d(on)}$, t_r

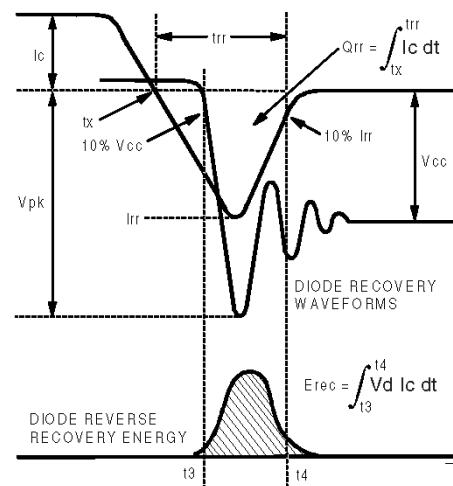


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining E_{rec} , t_{rr} , Q_m , I_{rr}

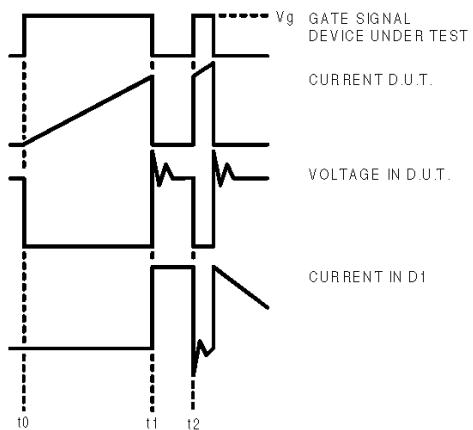


Figure 18e. Macro Waveforms for Figure 18a's Test Circuit

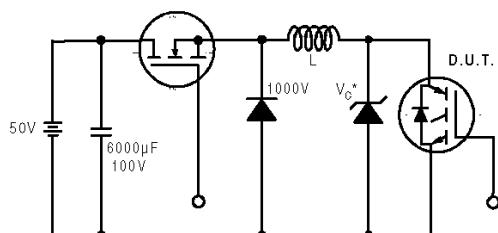


Figure 19. Clamped Inductive Load Test Circuit

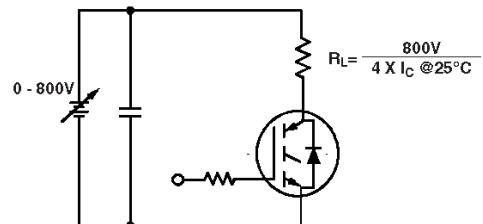


Figure 20. Pulsed Collector Current Test Circuit

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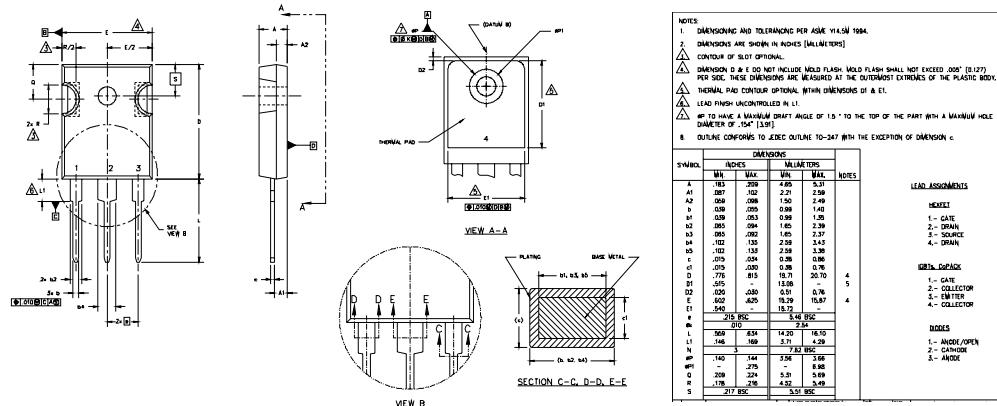
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Notes:

- ① Repetitive rating: $V_{GE}=20V$; pulse width limited by maximum junction temperature (figure 20)
- ② $V_{CC}=80\% (V_{CES})$, $V_{GE}=20V$, $L=10\mu H$, $R_G=10\Omega$ (figure 19)
- ③ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.
- ④ Pulse width $5.0\mu s$, single shot.

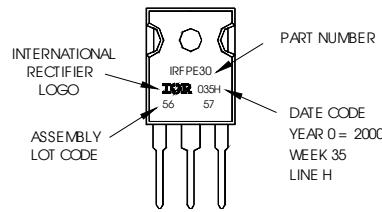
TO-247AC Package Outline

Dimensions are shown in millimeters (inches)



TO-247AC Part Marking Information

EXAMPLE: THIS IS AN IRFPE30
WITH ASSEMBLY
LOT CODE 5657
ASSEMBLED ON WW.35, 2000
IN THE ASSEMBLY LINE "H"
Note: "P" in assembly line
position indicates "Lead-Free"



Data and specifications subject to change without notice.

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IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105
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